APPLICA	BLE STAN	DARD									
	OPERATING TEMPERATUR	RE RANGE	-55 °C TO 85 °C (1)			STORAGE TEMPERATURE RANGE		IGF	-10 °C TO 60	C (2)	
RATING					STC	STORAGE HUMIDITY					2)
	VOLTAGE					ANGE PERATING HUMIDITY		TY	40 % TO 70	7∕0 (-)
	CURRENT		1			RANGE		·	RELATIVE HUMIDITY 8		max
	CURRENT		3 A (MF CONTACT)						(NOT DEWED)		
			· · · · · · · · · · · · · · · · · · ·	IFICA	TION	S			,		
IT	EM		TEST METHOD				RE	QUIF	REMENTS	QT	TA.
CONSTRI		1								1	1
GENERAL E	XAMINATION	VISUALL	Y AND BY MEASURING INS	STRUMEN	NT.	ACCO	RDING TO	O DRA	WING.	×	×
MARKING		CONFIRMED VISUALLY.								×	×
	C CHARAC										
CONTACT RESISTANCE		100 mA(DC OR 1000Hz)			1	SIGNAL CONTACT : 90 m Ω MAX. MF CONTACT : 30 m Ω MAX.				×	-
INSULATION RESISTANCE		250 V DC.				1000 MΩ MIN.				×	-
VOLTAGE PROOF		300 V AC FOR 1 min.				NO FLASHOVER OR BREAKDOWN.				×	1-
MECHANI	ICAL CHAR	ACTERI	STICS		•						•
INSERTION AND		MEASURED BY APPLICABLE CONNECTOR.			1	INSERTION FORCE: 40 N MAX.					_
WITHDRAWAL FORCES MECHANICAL		500 TIMES INSERTIONS AND EXTRACTIONS.				WITHDRAWAL FORCE: 4 N MIN. 1 CONTACT RESISTANCE:				×	<u> </u>
OPERATION VIBRATION		COO TIMES INSERTIONS AND EXTRACTIONS.			. '	SIGNAL CONTACT : 100 mΩ MAX.				^	
						MF CONTACT : 40 m Ω MAX.					
						② NO DAMAGE, CRACK AND LOOSENESS					
		FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min				OF PARTS. ① NO ELECTRICAL DISCONTINUITY OF					+_
· ibi o ti ioit			AMPLITUDE : 0.75 mm, 10 (1 με		IOAL I	5100014111401111 01	×	
		FOR 3 DIRECTIONS.				② NO DAMAGE, CRACK AND LOOSENESS					
SHOCK		490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.				OF	PARTS.			×	-
FN\/IRON	MENTAL C		TERISTICS	IONS.							
DAMP HEAT			DAT 40±2°C, 90 ~ 99	5 %. 96	h.	① COI	NTACT R	RESIST	ANCE:	×	T
(STEADY STATE)						SIGNAL CONTACT : 100 m Ω MAX.					
RAPID CHANGE OF		TEMPERATURE -55 → +85 °C				MF CONTACT : $40 \text{ m}\Omega$ MAX.				×	-
TEMPERATI	JRE	TIME 30 → 30 min. UNDER 5 CYCLES.			ľ	② INSULATION RESISTANCE :1000 MΩ MIN.					
		(RELOCATION TIME TO CHAMBER:WITHIN 2~3 MIN)				③ NO DAMAGE, CRACK AND LOOSENESS					
		,					PARTS.				
SULFUR DIC	OXIDE	EXPOSEI	D AT 25±2°C, 75±5%RH, 2	5 PPM F	OR	NO HE	AVY COF	RROSI	ION.	×	-
		(TEST STANDARD: JIS C 60068)									
RESISTANCE TO		1)REFLOW SOLDERING :				NO DEFORMATION OF CASE OF					-
SOLDERING HEAT SOLDERABILITY		PEAK TMP: 260°CMAX				EXCESSIVE LOOSENESS OF THE TERMINAL.					
		REFLOW TMP: 220°CMIN FOR 60sec 2) SOLDERING IRONS: 360°C MAX, FOR 5 sec.				LIVIVII	11/\L.				
		SOLDERING IRONS : 350 C MAX. FOR 5 SEC.				A NEW	UNIFOR	M COA	ATING OF SOLDER	×	+-
		240±3°C FOR IMMERSION DURATION, 3 sec.			-·	SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.					
						SUKFA	CE REIN	G IIVIIVI	EKSEU.		
COUN	IT D	ESCRIPTI	ON OF REVISIONS		DESIG	ESIGNED			CHECKED	DA	TE
/O\											
REMARKS (1) INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING.						APPROVED			HS. OKAWA 1		08.30
		ANS A LONG-TERM STORAGE STATE SED PRODUCT BEFORE ASSEMBLY TO PCB. RRENT APPLIES TO PER CONTACT.				CHECKED DESIGNED DRAWN		(ED	KI. HIROKAWA	11. (08. 30
								ved [TH. SANO 11		08. 30
Holoss -0	omulas are i	find f	ad refer to US C 5402					v _N †	TH, SANO	11, 08, 30	
Unless otherwise specified, refer to JIS-C-5402.											
		AT:Assurance Test X:Applicable Test				DRAWING NO.		FΧ	ELC4-334391-00 X18-60S-0, 8SV20		
HS					FARI	INU.				^	
HIR		OSE ELECTRIC CO., LTD.			CODE	ODE NO.		CL579-0031-3-00			1/1